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Z-Plane, Inc. and Elma Bustronic Win “Best of Show” Award at AdvancedTCA Summit

ATCA Backplane with Z-Plane Links wins Best Hardware Product

PALO ALTO, California, Nov 18, 2009 – Z-Plane, Inc., a technology-based high-speed electronic packaging and interconnection technology company, in concert with Elma Bustronic Corporation, an industry leading designer and manufacturer of high performance backplanes, won the Best of Show award at the AdvancedTCA Summit in Santa Clara CA on Oct 27-29. The winning ATCA Backplane was produced by Elma Bustronic and utilized performance enhancing Z-Plane Links mounted on the rear of the backplane PCB.

The Z-Plane/Bustronic ATCA backplane with Links won the award for its significant improvement in performance of an existing technology. The new backplane offers up to triple the performance of traditional versions of the backplane architecture at a reduced cost. This performance is achieved using the Z-Plane Links which carry the high-speed, long trace signals via small PCB boards which plug directly into the rear side of the backplane. The basic, shorter trace signal lines are left on the backplane, reducing the overall layer count while improving signal integrity.

“This award is significant to Z-Plane, because it represents industry recognition of our technology,” said Chuck Byer, President and CEO of Z-Plane, Inc. “Z-Plane plans to expand this evolutionary technology, offering creative systems solutions for AdvancedTCA and other architectures.”

About Z-Plane, Inc.:

Founded in 2008, Z-Plane™ Inc. is a technology-based high-speed electronic packaging and interconnection technology company, which was established to develop, market, and manufacture high-speed backplane interconnection solutions. Z-Plane™ Inc. will provide evolutionary packaging technology for high-speed telecommunications and computing equipment, including routers, servers, and switches with data rates from 40 Giga-bits per second per channel (or 40G) to more than 100G. Z-Plane™ packaging technologies focus on chip-to-chip interactions and include the backplane design, the backplane connectors, and the daughter card design. For further information, please see www.z-planeinc.com